L Number		Search Text Mizuochi-Masaki.in.	DB USPAT; US-EGPUB;	Time stamp 2003/04/24 09:30
-	74	Fukushima-Yoshimasa.in.	ESC; JPO USEAT; US-EGEUE;	1003/04/24 09:30
-	21	Fukushima-Yoshimasa in. and chamber	EEC; JPO USEAT; US-EGEUE;	2003/04/24 10:34
-	į	Invoe-Minsuru.in.	HEC; JPC USEAT; US-EGEUE; HEC; JPC	2003/04/24 09:31
-	595:	050[492.1.cmls. 250/492.2 ccls. 15  490.3.cdls. 050/441.11.ccls.	USEAT; US-EGEUB; EEC; SPC	2003/04/24 09:32
-	1634	2:1 442.1.pdls. 150/492.2.pols. .5 4 0.3.ppls. 200/442.11.pols.) and chardes	USEAT, US-EGPUR; EFD; JPG	2000,104124 09:3€
-	871:	1250/492.1.cols. [50]492.2.cols. .5/4(2.3.cols. [50]444]2/cols.) and	USFAT; US-PGPUF; EEL; JPC	2003 104 124   09:33
-	11:	250 4)C.1.cols. Fig. 492.2 cols. L5044Pd.(.cols. Ff (441.11.cols.) and redess03 proceed same (ring annul93))	ULIAT; UL-FGPUE; EEI; JPI	11000,704,124,09:34
-	2	196 44.11.ctls. 200(432.2.ccls. 259/491.5 ccls. 25 (441.11.ccls.) and chambers and (259/44.11.ccls. 259/491.1.ccls. 259/492.5.ccls. 259/441.11.ccls. and table) and 5 266/441.11.ccls. 259/492.3.ccls. 259/49.2.2.ccls. 259/441.11.ccls.) and	DEFAT; UE-EGEUE; EED; JEC	2000,104 124 09:36
-	i	<ul> <li>recover 13 groover some vrung annul\$?)))</li> <li>Farushim (Vosnimara in. and ((groove ring))</li> <li>rame recovers\$5)</li> </ul>	USEAT; US-EGPUE; EET; JFC	2000/04/24 10:35
<del>-</del>	3	Fukushima-Yoshimasa.un. and (Egroove ring) same frecess\$? indentation outcut))	USTAT; US-EGPUB; EPI; JPI	2000,704 (24 10.37
-	1.1	Fukus).nmu-Yoshimasa.un. and ((annul\$3) same refoss\$3))	USEAT; US-IGPUB; EEL; JPC	2003 '04 '24 10:37
-	20107.	(groome bing annul\$3) same recess\$0)	USERT; US-EGEUE; EEL; JEC	2003/04/24 10:54
-	5422.	[errorse ring annulse same recess(5)) and chamber	UTEAT; UL-EGPUB; EET; JPC	2000,704 (24 10:39
-	2104;	<pre>+(parophy ring annul3% same recess\$3)) and pwafer substrate workplede;</pre>	USEAT; UE-MGFUE; EEU; JEC	2003/04/24 10:39
-	6114	<pre>i( un wore ring annui(3) same recess(3)) and (harmer) and ((( groome ring annul(3)) same recess(3)) and wafer substrate wordgr</pre>	USEAT; UE-PGPUE; EEC; JPC	2005/04/24 10:40
-	1537	.(. orrower ring annul\$3) same reces(\$3)) and thumber) and ((( orrowering annul\$3) same recess\$3)) and twafer substrate works(***e=***) and table	USEAT, USEGFUR; EPS: JFC	2005/34/34 10:49
-	2572	-(1 ournove ring annu.83) same recess\$3)) and chamber) and (((groome ring annul\$3)) came robes\$3)) and wafer substrate worstless ) and vacuum	USEAT; US-PGPUB; EP1; JP0	2003/04/24 10:40
-	848	( in owe ring annuls) same recess(3)) and harmer) and (( rroome ring annuls3) same recess(5)) and wafer substrate work; (**de))) and table and ((((groove ring annuls5)) same recess(3)) and chamber) and (groove ring annuls5) same recess(3) and (wafer substrate work; iede)) and vacuum)	USEAT; US-PGPUE; EPI, JPO	2003/64/24 10.40

- ;	139	(((((((groove ring annul\$3) same recess\$3)) and chamber) and ((((groove ring annul\$3) same recess\$3)) and (wafer substrate workpieze))) and table and ((((((groove ring annul\$1) same recess\$3)) and chamber and (((groove ring annul\$1) same recess\$3)) and (wafer substrate workpieze) and warulm() and (table with	USPAF; US-PGPUB; EPD; JPO	2003/04/24 10:	43
-	5.	<pre>(grative ring annulab) ((( ) arbore ring annulab) same rethard()) and chamber) and (()(groove ring annulab) same recess(3) and (wafer substrate workpiete)); and table and ((() (roove ring annulab) same recess(3)) and chamber and (() (arbore ring annulab) same recess(3)) and (wafer substrate workpiede) and valuem); and (table with retess(3))</pre>	USPAT; US-PGPUM; EPD; JPO	2603/34/24 10:	43
	3.2	()(() gro we ring annull3) same recess(3)) and chammer) and (()(groove ring annuls)) same recess(3) and wifer substrate wirepiece)) and table and (()(groove ring annuls3 same recess(3)) and chamber and (()groove ring annuls3 same recess(3)) and recess(3)) and (water substrate workprece). and valuum): and (table with (groove ring annuls) same recess(3)) and chamber) and (()groove ring annuls) same recess(3) and chamber) and (()groove ring annuls) same recess(3)) and (wifer substrate workprece) and carde) and (()(((groove ring annuls)) same recess(3)) and (wifer substrate workprece). and (wifer substrate workprece). and (wifer substrate	USEAT; USEPSPUE; EET; JFO	2603,'04'24 10.	43
- 5	702	recess(35)) ((gradum ring annul(3 same recess(3) and (link graph, protolothography)	USEAT; US-PGPUS, EEG; JEI	2003/04/24 10:	55
- 2	254	()(incove ring annul\$3) same recess\$3) and (lithography photolothography) (and chamber	US-PGPUB; EFO; JFO	2003/04/24 10:	55
- 1	177	(((groove ring annul\$3) same receso\$3) and (lithography photolothography)) and table	USEAT; USEPGPUE; EEG; JPC	2003/04/24 10:	58
-		<pre>((( proceed ring annull)) came recession and (lithography photolothography) and chamber and (( process ring annull) same recesser) and (lithography photolothography canditalle)</pre>	UdeAT; UdePGPUE, Ead; Jac	2003/04/24 11/0	G1
- 317		recession with (water tubifrate workplede)	USPAT; US-PGPUP, ESC; JFC	2000/04/24 11/	02
- 71	150	<pre>(rereas\$3 with (uaser substrate workpiwde) and redexs\$5 same (groome sing annul@r)</pre>	USBAT; US PGPUB, EBC, JFC	2003/04/24 11:	
- 71	150	<pre>(recess33 with (wafer sub trate workpicle) and (recess; with (wafer sub-trate workpiece)) and (recess3) came (groupe ring annul3))</pre>	USEAT; USEPGPUE, EPG; JPC	2001/04,24 11:0	03
- 18	.801	<pre>[(redeas\$3 with wafer substrate workpleded) and (recess\$1 with [wafer substrate workpieded) and (recess\$1 dame control vin the [3])</pre>	USEAT; US-PGPUE; EPC; JPC	2005/04,24 11 (	04
- 11	182	(groove ring annul\$3) () and chamber ((recess\$3 with (wafer substrate workpiece)) and (recess\$5 with (wafer substrate workpiece)) and (recess\$3 same (groove ring annul\$3)) )) and table	USFAT; US-PGPUE, EPG; JPO	2003/04/24 11:3	04

-	463	(((recess\$3 with (wafer substrate workpiece), and ((recess\$3 with (wafer substrate workpiece)) and (recess\$3 same (growering annul\$3))) and chamber) and ((recess\$5 with (wafer substrate workpiece)) and (recess\$3 with wafer substrate workpiece)) and recess\$3 same	USPAT; US-PGFUB, EPU; JFI	2003)04/24 11.04
-	67	<pre>(greate ring annul\$1() )) and table) (( re ess\$3 with wafer substrate wor*press) and ((recess\$3 with wafer sub-trate workpiece ( and rece: \$1 same (greate ring annul\$1() )) and chamber) and ((recess\$6 with (wafer substrate wor*press) and ((recess\$3 with wafer substrate workpiece() and reces \$3 same (greate ring annul\$2() )) and table)) and lith graph\$2</pre>	USPAT; US PSPUE; EP ; JFI	2003/04/24 11:29
-	21780	(vicuum evacuat\$3) with (ring annul\$3)	UHPAF, UH PGPUE, EPO; JET	2003/04/24 11:35
-	450	((rapidum eracuat§3) with (rung simul§3)) same table	USEAT; USEAT;	2003/04/24 11:36
-	1355	((vacuum evacuat\$3) with (ring annul\$3)) same recess\$3	EBW; JEI USFAT; US-PSPUB; EBW; JEI	0003,04,24 11:36
-	29	((::::::::::::::::::::::::::::::::::::	USEAT, US-PSPUE; EE; JEI	1003/04/24 11:37
-	1~.,	73 Nertholm.	UEFAT, UE PGPUE, EPH, JFI	1003,04,114 12:39
-	112	73 6k3.pcls. and table	USTAT, US-PGPUE, BEO; JEI	1003,704,114 12:30
-	4.2	73 Mer. pols. and (groove armul\$) recess\$3)	USEAT; USEPSPUB; EPD; JET	1003/04/24 12:34
-	10078	43: U.upls. and table	USEAT, USEPSPUE, EPO; JES	1003,704,734 13:50
-	484	(418 Cipcle, and table ) and ((vacuum evatut92) same (ring annul;3 growe))	USFAT; US-PGPUE, EPO; JEC	2003/04/24 12:51
-	484	((438)%.ccis. and table ) and (macuum evannt03) same (ring annul;3 growve))) and table	USFAT; US-PGPUB; EP:; JFI	1003, 04, 24 12:51
-	121	<pre>()43% 0.csis. and table ) and (macuum embout10) same (ring annul(3 grame))) and recession</pre>	USTAT; U: PGPUE; EP: JFI	003/04/24 12:51
-	121	() 4:8 \$.pdls. and table ) and vacuum	USPAT; US-PGPUE; EP , UFI	7003,04/24 12:53
-	446149	(hitachi carmon).as.	USFAT; US-PGPUE; ED ; JEG	1003/04/24 12:53
÷	19566	((hita.hi dannon).as.) and chamber	USTAT; UE-PGPUE; EE , JEC	1003/04/24 12:53
-	66	(( hitaihi cannon).as.) and chamber) and (table with (grocve annulus ring))	UEFAT; UE-PGPUE; EPC; JPC	.003/04/24 18:54
-	0	lithegraphy same table same groove same relects	USPAT, US-PGPUE, EPO; JPO	2003/04/24 13.21